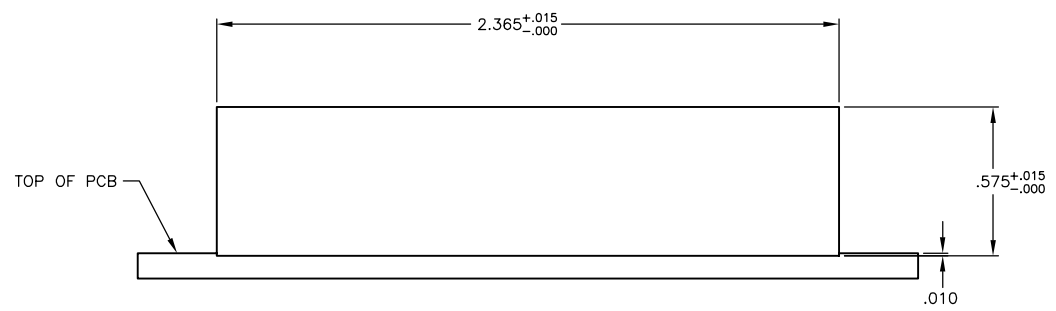
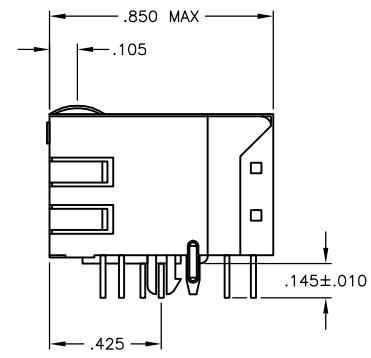
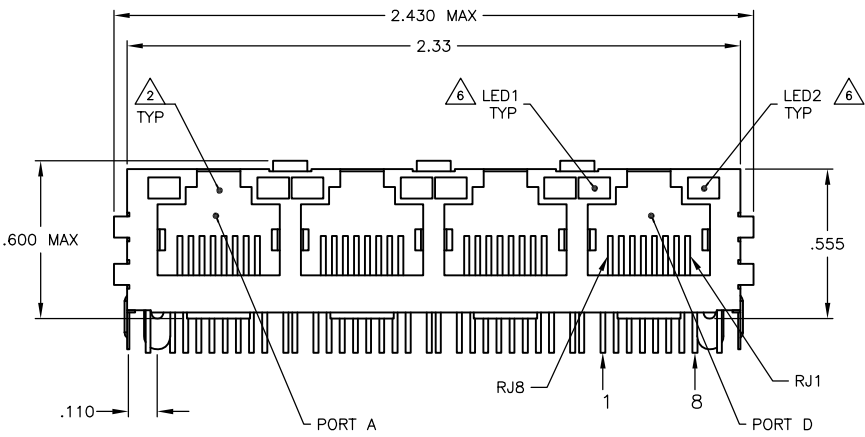
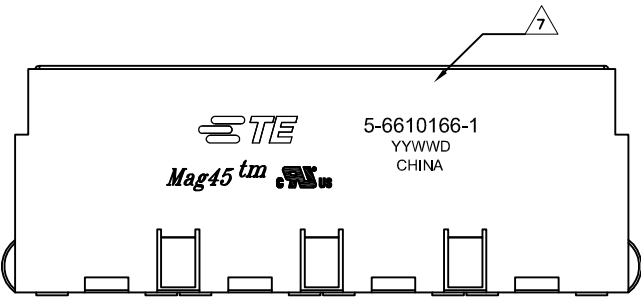


MECHANICAL:



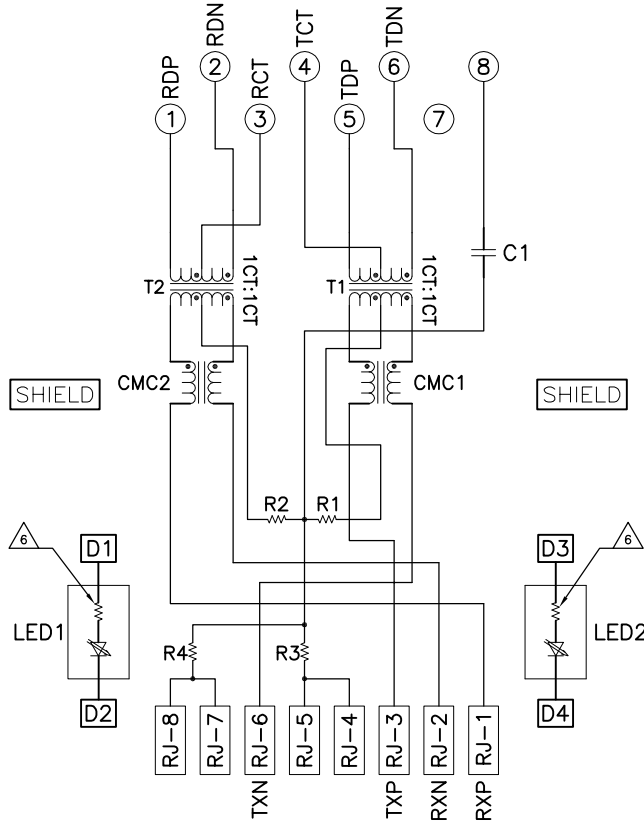
1X4 SUGGESTED PANEL CUTOUT

- 1. MATERIALS:
 - HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30 μ INCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100 μ INCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50 μ INCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50 μ INCH MIN HARD GOLD FINISH PLATE.
 - SOLDER TAILS WITH 100 μ INCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80 μ INCH SILVER OVER 4.0 μ INCH NICKEL UNDERPLATE OVER 40 μ INCH COPPER UNDERPLATE. POST-PLATED WITH 100 μ IN MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- 2. RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
- 3. MAGNETICS
 - IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 - OPEN CIRCUIT INDUCTANCE (OCL): 350 μ H MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 - 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 - 12dB MIN FROM 60.1MHz TO 80MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 - 33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 23.5.1.1, ITEM b.
- 4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
- 5. INDICATED CONNECTIONS ARE FOR HUB CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL AND SUPPORT AUTO-MDI/MDIX.
- 6. LEDs WITH BUILT-IN RESISTOR
 - LEDs ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.
 - LED COLOR: DOMINANT WAVELENGTH (AD): GREEN 568 nm TYP @ VF=5V
 - FORWARD CURRENT (IF): GREEN 12mA TYP @ VF=5V
 - DOMINANT WAVELENGTH (AD): YELLOW 588 nm TYP @ VF=5V
 - FORWARD CURRENT (IF): YELLOW 13mA TYP @ VF=5V
- 7. TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
- 8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS. PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

GREEN	YELLOW	5-6610166-1
LED1 \triangle 6	LED2 \triangle 6	PART NUMBER

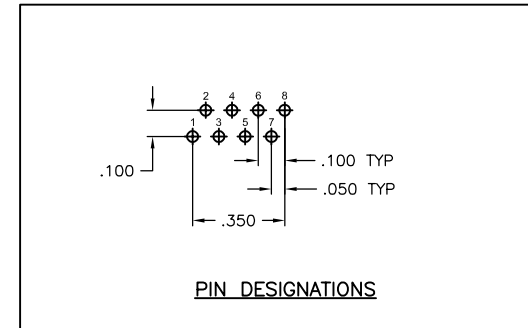
THIS DRAWING IS A CONTROLLED DOCUMENT.		REV. 5 ATTACIA - (REVISION)	DATE
DIMENSIONS:		DR. S. PAROLE	DATE
MATERIAL:		DR. S. PAROLE	DATE
FINISH:		DR. S. PAROLE	DATE
CUSTOMER DRAWING		108-2100	1X4 MAG45(TM) MODULAR JACK, 7H5 SCHEMATIC, 768P9 MAGNETIC CIRCUIT, SHIELDED, DECOUPLING CAPACITOR, WITH RESISTOR LEADS
SCALE 4:1		SIZE A1	00779
SHEET 1		OF 2	REV. C

766P9 MAGNETIC CIRCUIT

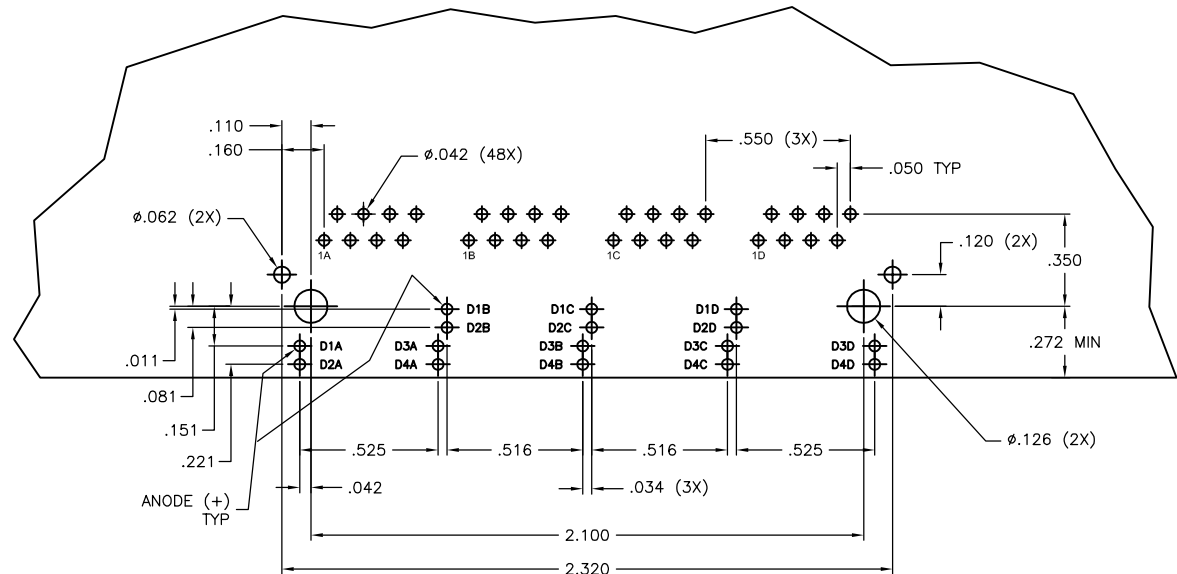


C1=1000pF, 2kV CAPACITOR

R1-R4 = 75 OHMS, 1/16W RESISTORS



PIN DESIGNATIONS



SUGGESTED PCB LAYOUT
 (Component Side)

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV. 05 ATTACIA - 00000000		DATE	
DIMENSIONS:		UNIT: MILLIMETER		SCALE	
MATERIAL:		FINISH:		CUSTOMER DRAWING	
DRAWN BY:		CHECKED BY:		DATE:	
DESIGNED BY:		APPROVED BY:		DATE:	
PROJECT NO.:		108-2100		APPLICATION SPEC:	
SIZE:		A1		SCALE: 4:1	
PART NO.:		00779		REV. 2	
DESCRIPTION:		1X4 MAG45(TM) MODULAR JACK, 7HS SCHEMATIC, 766P9 MAGNETIC CIRCUIT, SHIELDED, DECOUPLING CAPACITOR, WITH RESISTOR LEADS		REV. 2	
DRAWING NO.:		6610166		REV. 2	